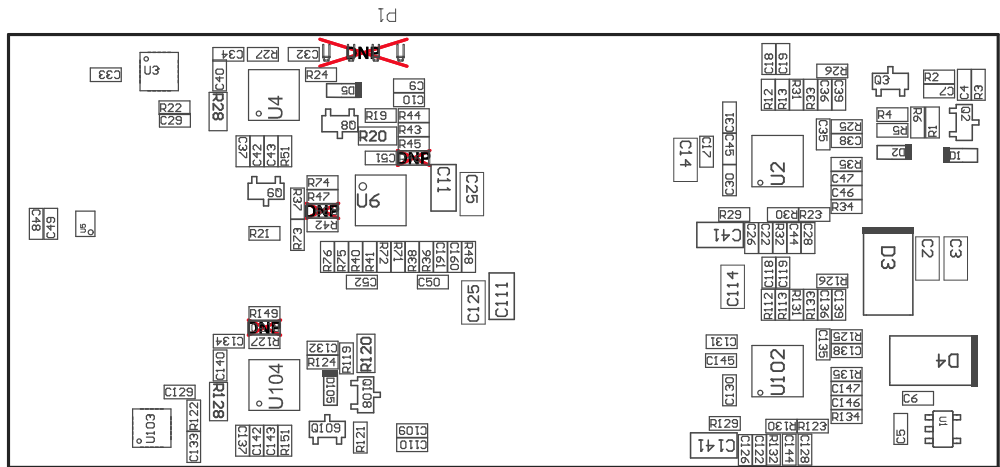


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40312		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/6/2017	10:39:05 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40312	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40312		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/6/2017 10:39:07 AM		TEXAS INSTRUMENTS

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